

Pb Free Plating Product

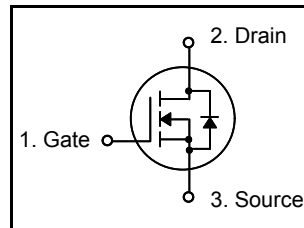
## W20NB50



20A,500V Heatsink N-Channel Type Power MOSFET

## Features

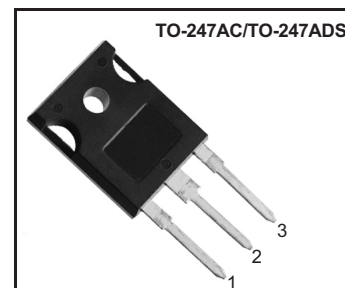
- $R_{DS(on)}$  (Max 0.24  $\Omega$ )@ $V_{GS}=10V$
- Gate Charge (Typical 130nC)
- Improved dv/dt Capability
- High ruggedness
- 100% Avalanche Tested

 $BV_{DSS} = 500V$  $R_{DS(ON)} = 0.24 \text{ ohm}$  $I_D = 20A$ 

## General Description

This N-channel enhancement mode field-effect power transistor using THINKI Semiconductor advanced planar stripe, DMOS technology intended for off-line switch mode power supply.

Also, especially designed to minimize  $r_{ds(on)}$  and high rugged avalanche characteristics. The TO-247AC pkg is well suited for adaptor power unit and small power inverter application.

Absolute Maximum Ratings  $T_C = 25^\circ\text{C}$  unless otherwise noted

| Symbol         | Parameter                                                                     | Value       | Units               |
|----------------|-------------------------------------------------------------------------------|-------------|---------------------|
| $V_{DSS}$      | Drain-Source Voltage                                                          | 500         | V                   |
| $I_D$          | Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )                       | 20          | A                   |
|                | - Continuous ( $T_C = 100^\circ\text{C}$ )                                    | 12.5        | A                   |
| $I_{DM}$       | Drain Current - Pulsed (Note 1)                                               | 80          | A                   |
| $V_{GSS}$      | Gate-Source Voltage                                                           | $\pm 30$    | V                   |
| $E_{AS}$       | Single Pulsed Avalanche Energy (Note 2)                                       | 1050        | mJ                  |
| $I_{AR}$       | Avalanche Current (Note 1)                                                    | 20          | A                   |
| $E_{AR}$       | Repetitive Avalanche Energy (Note 1)                                          | 23.5        | mJ                  |
| dv/dt          | Peak Diode Recovery dv/dt (Note 3)                                            | 4.5         | V/ns                |
| $P_D$          | Power Dissipation ( $T_C = 25^\circ\text{C}$ )                                | 235         | W                   |
|                | - Derate above $25^\circ\text{C}$                                             | 1.88        | W/ $^\circ\text{C}$ |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                                       | -55 to +150 | $^\circ\text{C}$    |
| $T_L$          | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300         | $^\circ\text{C}$    |

## Thermal Characteristics

| Symbol          | Parameter                               | Typ  | Max  | Units              |
|-----------------|-----------------------------------------|------|------|--------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case    | --   | 0.53 | $^\circ\text{C/W}$ |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink        | 0.24 | --   | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | --   | 40   | $^\circ\text{C/W}$ |

**Electrical Characteristics** $T_C = 25^\circ\text{C}$  unless otherwise noted

| Symbol                         | Parameter                                 | Test Conditions                                                   | Min | Typ  | Max  | Units              |
|--------------------------------|-------------------------------------------|-------------------------------------------------------------------|-----|------|------|--------------------|
| <b>Off Characteristics</b>     |                                           |                                                                   |     |      |      |                    |
| $BV_{DSS}$                     | Drain-Source Breakdown Voltage            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$               | 500 | --   | --   | V                  |
| $\Delta BV_{DSS} / \Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$ | --  | 0.55 | --   | $V/^\circ\text{C}$ |
| $I_{DSS}$                      | Zero Gate Voltage Drain Current           | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$                      | --  | --   | 10   | $\mu\text{A}$      |
|                                |                                           | $V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$                  | --  | --   | 100  | $\mu\text{A}$      |
| $I_{GSSF}$                     | Gate-Body Leakage Current, Forward        | $V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$                       | --  | --   | 100  | nA                 |
| $I_{GSSR}$                     | Gate-Body Leakage Current, Reverse        | $V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$                      | --  | --   | -100 | nA                 |

**On Characteristics**

|              |                                   |                                                      |     |     |      |          |
|--------------|-----------------------------------|------------------------------------------------------|-----|-----|------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$      | 2.0 | --  | 4.0  | V        |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10\text{ V}, I_D = 10.0\text{ A}$          | --  | 0.2 | 0.24 | $\Omega$ |
| $g_{FS}$     | Forward Transconductance          | $V_{DS} = 50\text{ V}, I_D = 10.0\text{ A}$ (Note 4) | --  | 18  | --   | S        |

**Dynamic Characteristics**

|           |                              |                                                                      |    |      |      |    |
|-----------|------------------------------|----------------------------------------------------------------------|----|------|------|----|
| $C_{iss}$ | Input Capacitance            | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$<br>$f = 1.0\text{ MHz}$ | -- | 4590 | 6000 | pF |
| $C_{oss}$ | Output Capacitance           |                                                                      | -- | 380  | 460  | pF |
| $C_{rss}$ | Reverse Transfer Capacitance |                                                                      | -- | 60   | 80   | pF |

**Switching Characteristics**

|              |                     |                                                                                        |    |     |     |    |
|--------------|---------------------|----------------------------------------------------------------------------------------|----|-----|-----|----|
| $t_{d(on)}$  | Turn-On Delay Time  | $V_{DD} = 250\text{ V}, I_D = 20\text{ A},$<br>$R_G = 25\text{ }\Omega$<br>(Note 4, 5) | -- | 50  | 120 | ns |
| $t_r$        | Turn-On Rise Time   |                                                                                        | -- | 150 | 310 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time |                                                                                        | -- | 380 | 770 | ns |
| $t_f$        | Turn-Off Fall Time  |                                                                                        | -- | 180 | 370 | ns |
| $Q_g$        | Total Gate Charge   | $V_{DS} = 400\text{ V}, I_D = 20\text{ A},$<br>$V_{GS} = 10\text{ V}$<br>(Note 4, 5)   | -- | 130 | 170 | nC |
| $Q_{gs}$     | Gate-Source Charge  |                                                                                        | -- | 20  | --  | nC |
| $Q_{gd}$     | Gate-Drain Charge   |                                                                                        | -- | 45  | --  | nC |

**Drain-Source Diode Characteristics and Maximum Ratings**

|                 |                                                       |                                                                                           |    |     |     |    |
|-----------------|-------------------------------------------------------|-------------------------------------------------------------------------------------------|----|-----|-----|----|
| I <sub>S</sub>  | Maximum Continuous Drain-Source Diode Forward Current |                                                                                           | -- | --  | 20  | A  |
| I <sub>SM</sub> | Maximum Pulsed Drain-Source Diode Forward Current     |                                                                                           | -- | --  | 80  | A  |
| V <sub>SD</sub> | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 20 A                                              | -- | --  | 1.4 | V  |
| t <sub>rr</sub> | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 20 A,<br>dI <sub>F</sub> / dt = 100 A/μs (Note 4) | -- | 480 | --  | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge                               |                                                                                           | -- | 7.7 | --  | μC |

**Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 5.1\text{ mH}, I_{AS} = 20\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 20\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

## Typical Characteristics

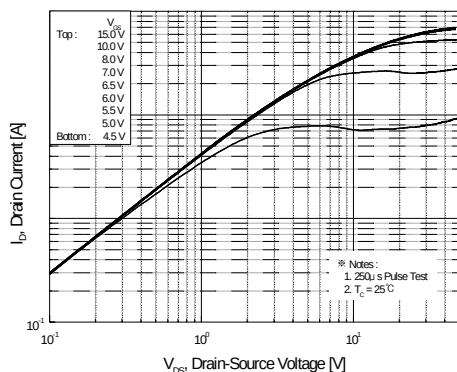


Figure 1. On-Region Characteristics

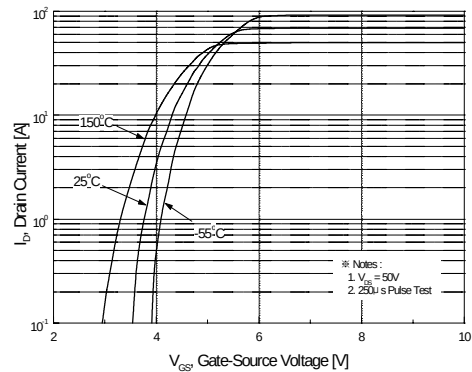


Figure 2. Transfer Characteristics

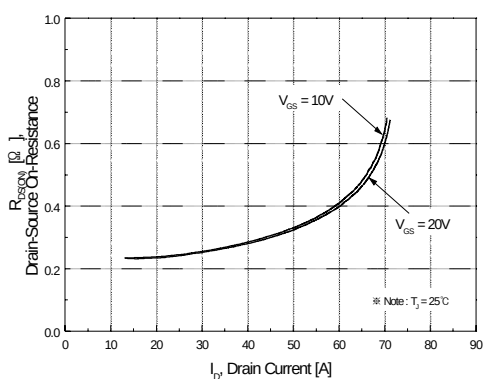


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

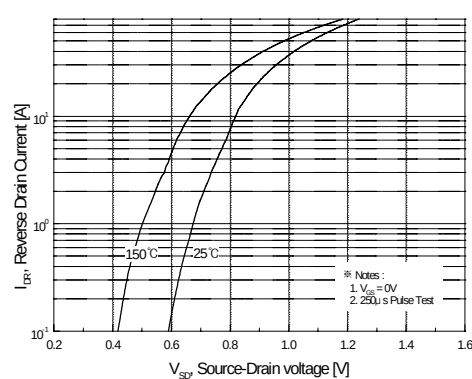


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

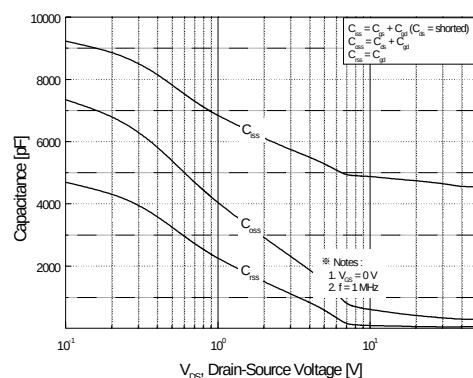


Figure 5. Capacitance Characteristics

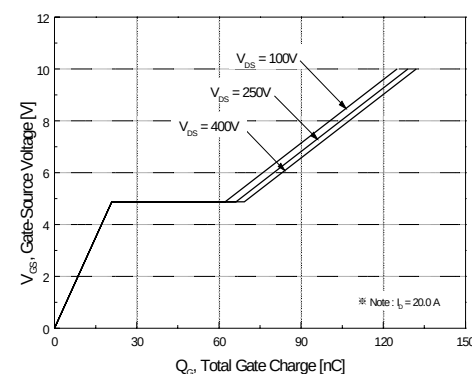


Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)

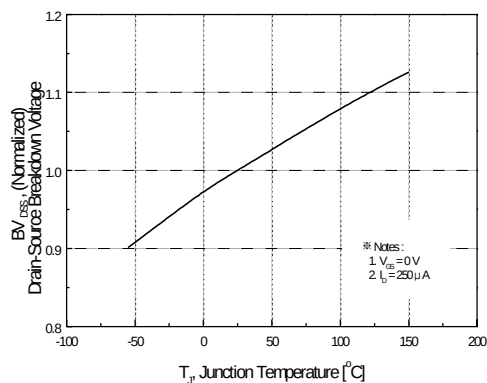


Figure 7. Breakdown Voltage Variation vs Temperature

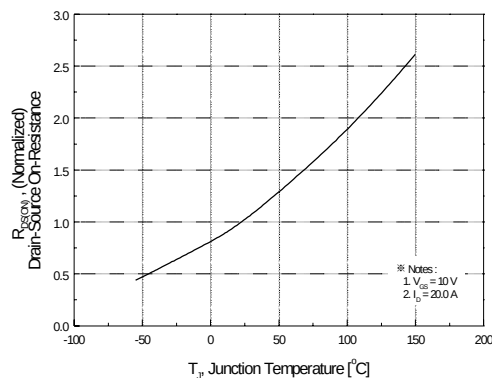


Figure 8. On-Resistance Variation vs Temperature

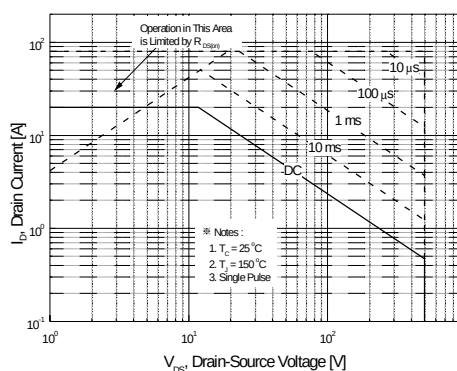


Figure 9. Maximum Safe Operating Area

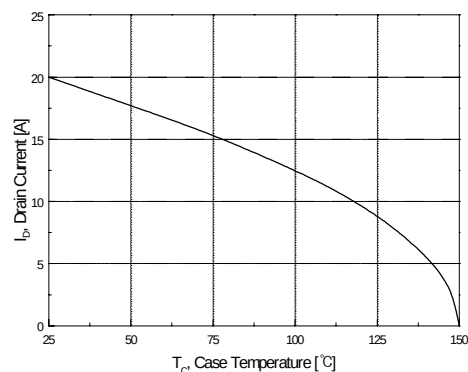


Figure 10. Maximum Drain Current vs Case Temperature

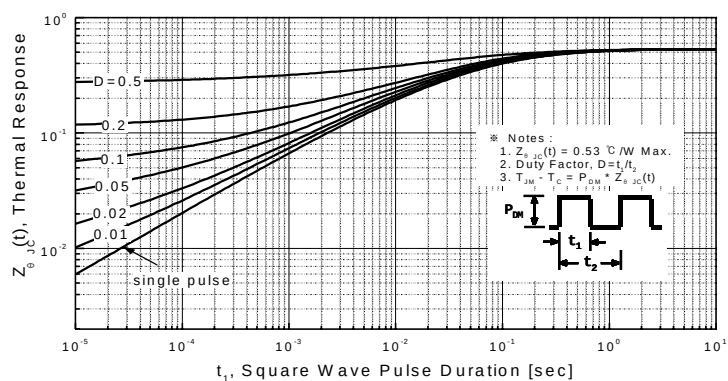
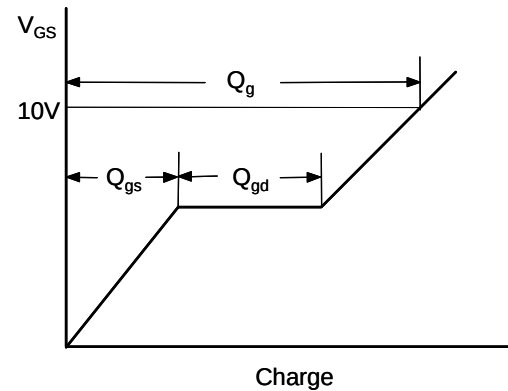
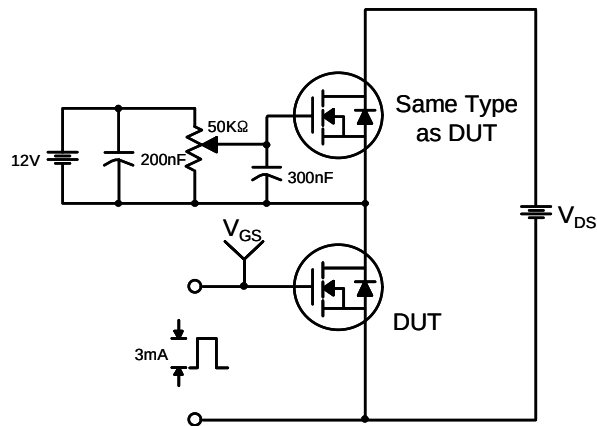
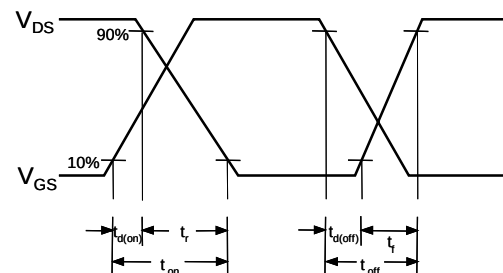
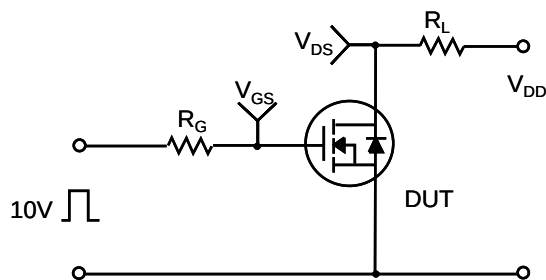


Figure 11. Transient Thermal Response Curve

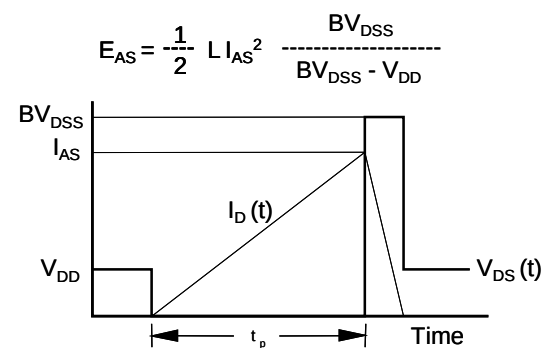
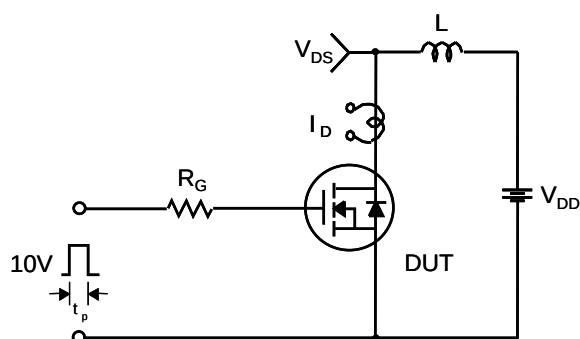
Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveforms



Unclamped Inductive Switching Test Circuit &amp; Waveforms



Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms